

ABSTRACT

CLEANING FORMULATIONS

A composition useful for removing residue from a semiconductor substrate comprising in effective cleaning amounts: from about 55 to 80% by weight of water; from
5 about 0.3 to about 5.0% by weight of EDTA; from about 10.0 to about 30.0% by weight of
an amine compound wherein the amine compound is selected from the group consisting
of a secondary amine, a tertiary amine, and mixtures thereof; from about 0.1 to about
5.0% by weight of a polyfunctional organic acid; from about 0.01 to about 8.0% by weight
of a fluoride ion source; from about 0 to about 60% by weight of a water-miscible organic
10 solvent; and from about 0 to about 15% by weight of a corrosion inhibitor.